

IEEE RAO R. TUMMALA ELECTRONICS PACKAGING AWARD

RECIPIENTS

(Formerly the IEEE Electronics Packaging Award)

- 2022 – DOUGLAS C.H. YU
Vice President, TSMC, Hsinchu,
Taiwan
“For contributions to the development of advanced packaging technologies and their implementation in high-volume manufacturing.”
- 2021 – CHIN C. LEE
Retired Professor, University of
California, Irvine, California, USA
“For contributions to new silver alloys, new bonding methods, flip-chip interconnect, and education for electronics packaging.”
- 2020 – MITSUMASA KOYANAGI
Senior Research Fellow, Tohoku
University, Sendai, Miyagi, Japan
“For pioneering contributions leading to the commercialization of 3D wafer and die level stacking packaging.”
- AND
- PETER RAMM
Head of Strategic Projects,
Fraunhofer EMFT, Bavaria, Germany
- 2019 – EPHRAIM SUHIR
Professor, Portland State
University, Portland, Oregon, USA
“For seminal contributions to mechanical reliability engineering and modeling of electronic and photonic packages and systems.”
- 2018 – WILLIAM CHEN
Fellow of ASE Group, Sunnyvale,
California, USA
“For contributions to electronic packaging from research and development through industrialization, and for his leadership in strategic roadmapping efforts.”
- 2017 – PAUL S. HO
Professor, The University of Texas at
Austin, Austin, Texas, USA
“For contributions to the materials science of packaging and its impact on reliability, specifically in the science of electromigration.”
- AND
- KING-NING TU
Distinguished Professor, Department
of Material Science & Engineering,
University of California at Los
Angeles, Los Angeles, California,
USA
- 2016 – MICHAEL PECHT
Director, Center for Advanced Life
Cycle Engineering, University of
Maryland, College Park, Maryland,
USA
“For visionary leadership in the development of physics-of-failure-based and prognostics-based approaches to electronic packaging reliability.”

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- 2015 - NASSER BOZORG-GRAYELI
President Technology and
Manufacturing Group, Intel
Corporation, Tempe, Arizona, USA
"For contributions to the advancement of
microelectronic packaging technology,
manufacturing, and semiconductor
ecosystems."
- 2014 - AVRAM BAR-COHEN
Distinguished University Professor of
Mechanical Engineering,
University of Maryland,
College Park, Maryland, USA
"For contributions to thermal design,
modeling, and analysis, and for original
research on heat transfer and liquid-phase
cooling."
- 2013 - JOHN LAU
ITRI Fellow, Industrial Technology
Research Institute (ITRI), Hsinchu,
Taiwan
"For contributions to the literature in advanced
solder materials, manufacturing for highly
reliable electronic products, and education in
advanced packaging."
- 2012 - MAURO WALKER
Senior Vice President and Director
of Manufacturing, Motorola
(Retired), Ocean Ridge, FL, USA
"For advancing electronic manufacturing,
technology and packaging worldwide through
technical innovation and cooperative
leadership in industry, government, academia
and professional organizations."
- 2011 - RAO R. TUMMALA
Endowed Chair Professor, Georgia
Institute of Technology, Packaging
Research Center, Atlanta, GA, USA
"For pioneering and innovative contributions to
package integration research, cross-
disciplinary education and globalization of
electronic packaging."
- 2010 – HERBERT REICHL
Full Professor at Faculty IV
Technische Univ Berlin
Berlin, Germany
"For contributions to the integration of
reliability in electronic systems, and leadership
in research and education in electronic
packaging."
- 2009 – GEORGE G. HARMAN
NIST Scientist Emeritus
Gaithersburg, MD, USA
"For achievements in wire bonding
technologies."
- 2008 – KARL PUTTLITZ SR.
President, Puttlitz Engineering
Consultancy, Wappingers Falls, NY
USA
"For pioneering achievements in flip chip
interconnection technology and for
semiconductor devices and packages"
- AND
PAUL A. TOTTA
Retired, IBM East Fishkill Facility,
East Fishkill, NY, USA

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| 2007 – DIMITRY GRABBE Worcester Polytechnic Institute Worcester, MA | "For contributions to the fields of electrical/electronic connector technology, and development of multi-layer printed wiring boards." |
| 2006 – C. P. WONG Regent's Professor at Georgia Institute of Technology, Atlanta, GA | "For contributions in advanced polymeric materials science and processes for highly reliable electronic packages." |
| 2005 – YUTAKA TSUKADA Manager of Packaging Technology Development Kyocera SLC Technologies Corp Shiga-Ken, Japan | "For pioneering contributions in micro-via technology for printed circuit boards, and for extending the feasibility of the direct flip-chip attachment process." |
| 2004 – JOHN W. BALDE Senior Consultant Interconnection Decision Consulting Flemington, NJ | "For lifetime contributions to tantalum film technology and the introduction of new electronic packaging technology to development and manufacturing." |